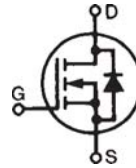


HiPerFET™ Power MOSFET Q2-Class

IXFL70N60Q2

(Electrically Isolated Tab)

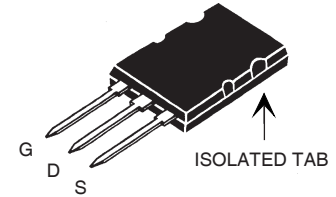


N-Channel Enhancement Mode
Avalanche Rated, Low Q_g , Low Intrinsic R_G
High dV/dt , Low t_{rr}

$V_{DSS} = 600V$
 $I_{D25} = 37A$
 $R_{DS(on)} \leq 92m\Omega$
 $t_{rr} \leq 250ns$

| Symbol | Test Conditions | Maximum Ratings | |
|---------------|--|-----------------|------------|
| V_{DSS} | $T_J = 25^\circ C$ to $150^\circ C$ | 600 | V |
| V_{DGR} | $T_J = 25^\circ C$ to $150^\circ C$, $R_{GS} = 1M\Omega$ | 600 | V |
| V_{GSS} | Continuous | ± 30 | V |
| V_{GSM} | Transient | ± 40 | V |
| I_{D25} | $T_C = 25^\circ C$ | 37 | A |
| I_{DM} | $T_C = 25^\circ C$, Pulse Width Limited by T_{JM} | 280 | A |
| I_A | $T_C = 25^\circ C$ | 35 | A |
| E_{AS} | $T_C = 25^\circ C$ | 5 | J |
| dV/dt | $I_S \leq I_{DM}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ C$ | 20 | V/ns |
| P_D | $T_C = 25^\circ C$ | 360 | W |
| T_J | | -55 ... +150 | $^\circ C$ |
| T_{JM} | | 150 | $^\circ C$ |
| T_{stg} | | -55 ... +150 | $^\circ C$ |
| T_L | 1.6 mm (0.063 in.) from Case for 10s | 300 | $^\circ C$ |
| T_{SOLD} | Plastic body for 10s | 260 | $^\circ C$ |
| F_C | Mounting Force | 40..120 / 9..27 | N/lb. |
| V_{ISOL} | 50/60 Hz, RMS $t = 1$ min $I_{ISOL} \leq 1$ mA $t = 1$ s | 2500 3000 | V~ V~ |
| Weight | | 8 | g |

ISOPLUS264



G = Gate D = Drain
S = Source

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- 2500V Electrical Isolation
- Fast Intrinsic Diode
- Avalanche Rated
- Low Q_g
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- DC-DC Converters
- Battery Chargers
- Switched-Mode and Resonant-Mode Power Supplies
- DC Choppers
- Temperature and Lighting Controls

| Symbol | Test Conditions ($T_J = 25^\circ C$, Unless Otherwise Specified) | Characteristic Values | | |
|--------------|---|-----------------------|------|---------------------|
| | | Min. | Typ. | Max. |
| BV_{DSS} | $V_{GS} = 0V$, $I_D = 1mA$ | 600 | | V |
| $V_{GS(th)}$ | $V_{DS} = V_{GS}$, $I_D = 8mA$ | 3.0 | | 5.5 V |
| I_{GSS} | $V_{GS} = \pm 30V$, $V_{DS} = 0V$ | | | ± 200 nA |
| I_{DSS} | $V_{DS} = V_{DSS}$, $V_{GS} = 0V$ $T_J = 125^\circ C$ | | | 100 μA 5 mA |
| $R_{DS(on)}$ | $V_{GS} = 10V$, $I_D = 35A$, Note 1 | | | 92 m Ω |

| Symbol | Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified) | Characteristic Values | | |
|--------------|---|-----------------------|------|--------------------|
| | | Min. | Typ. | Max. |
| g_{fs} | $V_{DS} = 10\text{V}, I_D = 35\text{A}$, Note 1 | 36 | 50 | S |
| C_{iss} | $V_{GS} = 0\text{V}, V_{DS} = 25\text{V}, f = 1\text{MHz}$ | | 12 | nF |
| C_{oss} | | | 1340 | pF |
| C_{rss} | | | 345 | pF |
| $t_{d(on)}$ | Resistive Switching Times $V_{GS} = 10\text{V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 35\text{A}$ $R_G = 1\Omega$ (External) | | 26 | ns |
| t_r | | | 25 | ns |
| $t_{d(off)}$ | | | 60 | ns |
| t_f | | | 12 | ns |
| $Q_{g(on)}$ | $V_{GS} = 10\text{V}, V_{DS} = 0.5 \cdot V_{DSS}, I_D = 35\text{A}$ | | 265 | nC |
| Q_{gs} | | | 57 | nC |
| Q_{gd} | | | 120 | nC |
| R_{thJC} | | | 0.35 | $^\circ\text{C/W}$ |
| R_{thCS} | | 0.15 | | $^\circ\text{C/W}$ |

Source-Drain Diode

| Symbol | Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified) | Characteristic Values | | |
|----------|---|-----------------------|------|---------------|
| | | Min. | Typ. | Max. |
| I_S | $V_{GS} = 0\text{V}$ | | | 70 A |
| I_{SM} | Repetitive, Pulse Width Limited by T_{JM} | | | 280 A |
| V_{SD} | $I_F = I_S, V_{GS} = 0\text{V}$, Note 1 | | | 1.5 V |
| t_{rr} | $I_F = 25\text{A}, V_{GS} = 0\text{V}$ $-di/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}$ | | | 250 ns |
| Q_{RM} | | | 1.2 | μC |
| I_{RM} | | | 8.0 | A |

Note: 1. Pulse test, $t \leq 300\mu\text{s}$, duty cycle, $d \leq 2\%$.

ISOPLUS264™ (IXFL) Outline

Note: Bottom heatsink meets

| SYM | INCHES | | MILLIMETERS | |
|-----|----------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | .190 | .205 | 4.83 | 5.21 |
| A1 | .102 | .118 | 2.59 | 3.00 |
| A2 | .046 | .055 | 1.17 | 1.40 |
| b | .045 | .055 | 1.14 | 1.40 |
| b1 | .087 | .102 | 2.21 | 2.59 |
| b2 | .111 | .126 | 2.82 | 3.20 |
| c | .020 | .029 | 0.51 | 0.74 |
| D | 1.020 | 1.040 | 25.91 | 26.42 |
| E | .770 | .788 | 19.56 | 20.09 |
| e | .215 BSC | | 5.46 BSC | |
| L | .780 | .820 | 19.81 | 20.83 |
| L1 | .080 | .102 | 2.03 | 2.59 |
| Q | .210 | .235 | 5.33 | 5.97 |
| Q1 | .490 | .513 | 12.45 | 13.03 |
| R | .150 | .180 | 3.81 | 4.57 |
| R1 | .100 | .130 | 2.54 | 3.30 |
| S | .668 | .690 | 16.97 | 17.53 |
| T | .801 | .821 | 20.34 | 20.85 |
| U | .065 | .080 | 1.65 | 2.03 |

Ref: IXYS CO 0128

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

| | | | | | | | | | | |
|--|-----------|-----------|-----------|-----------|--------------|--------------|--------------|--------------|--------------|-------------|
| IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: | 4,835,592 | 4,931,844 | 5,049,961 | 5,237,481 | 6,162,665 | 6,404,065 B1 | 6,683,344 | 6,727,585 | 7,005,734 B2 | 7,157,338B2 |
| | 4,850,072 | 5,017,508 | 5,063,307 | 5,381,025 | 6,259,123 B1 | 6,534,343 | 6,710,405 B2 | 6,759,692 | 7,063,975 B2 | |
| | 4,881,106 | 5,034,796 | 5,187,117 | 5,486,715 | 6,306,728 B1 | 6,583,505 | 6,710,463 | 6,771,478 B2 | 7,071,537 | |

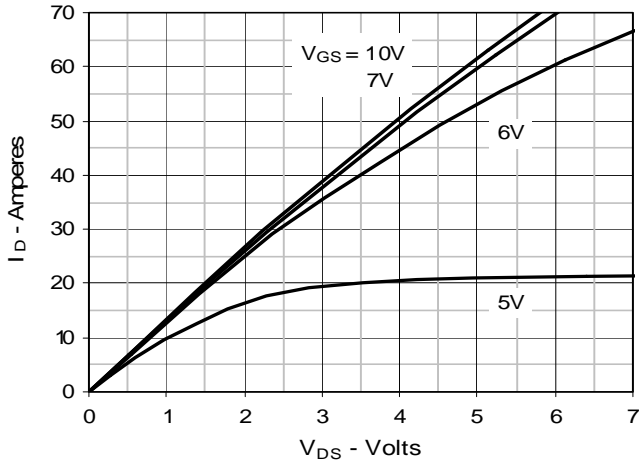
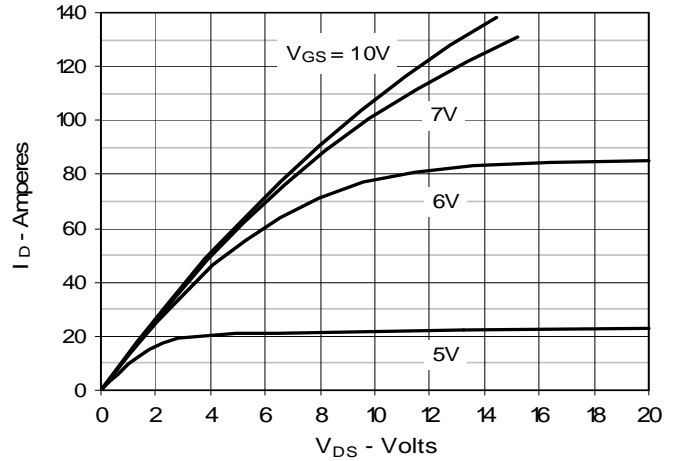
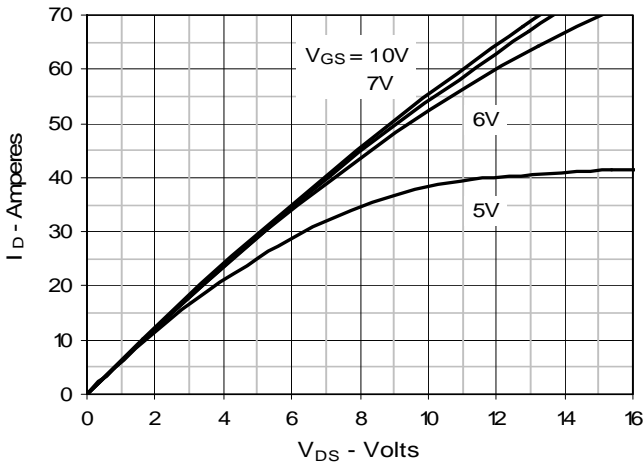
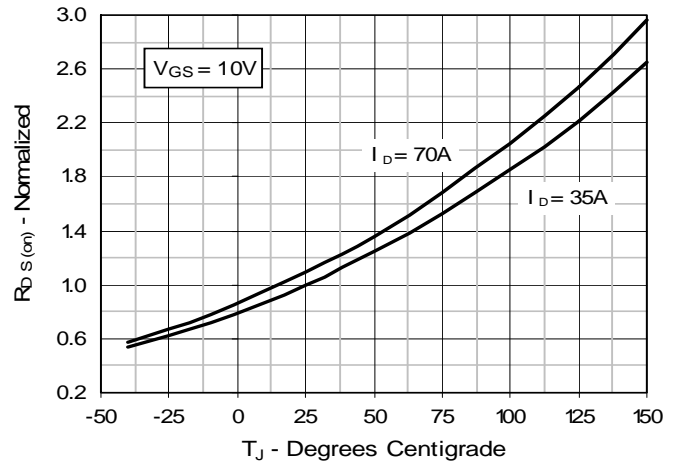
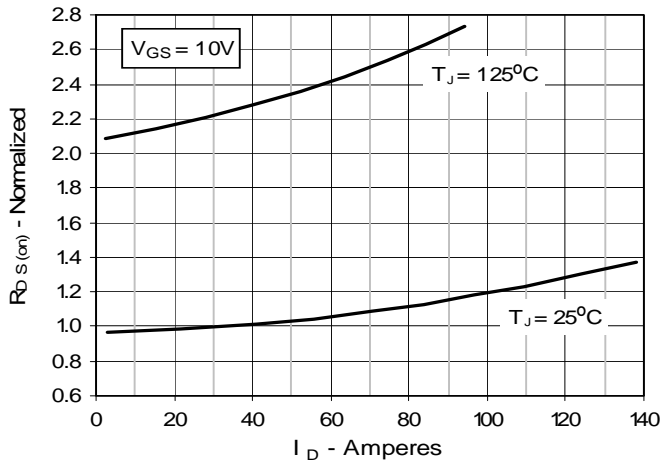
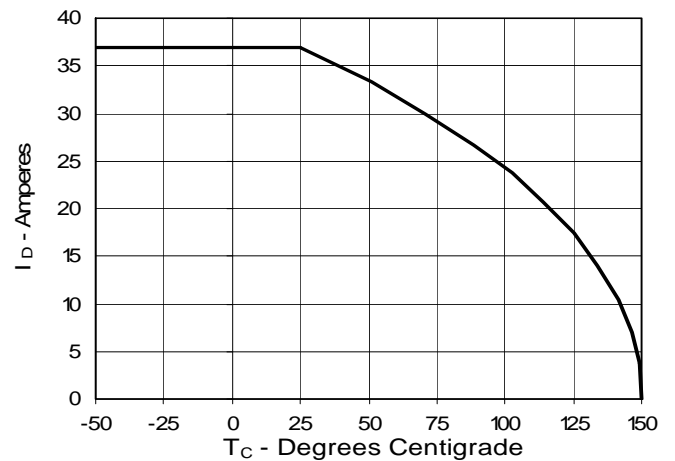
Fig. 1. Output Characteristics
 @ 25°C

Fig. 2. Extended Output Characteristics
 @ 25°C

Fig. 3. Output Characteristics
 @ 125°C

Fig. 4. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. Junction Temperature

Fig. 5. $R_{DS(on)}$ Normalized to 0.5 I_{D25} Value vs. I_D

Fig. 6. Drain Current vs. Case Temperature


Fig. 7. Input Admittance

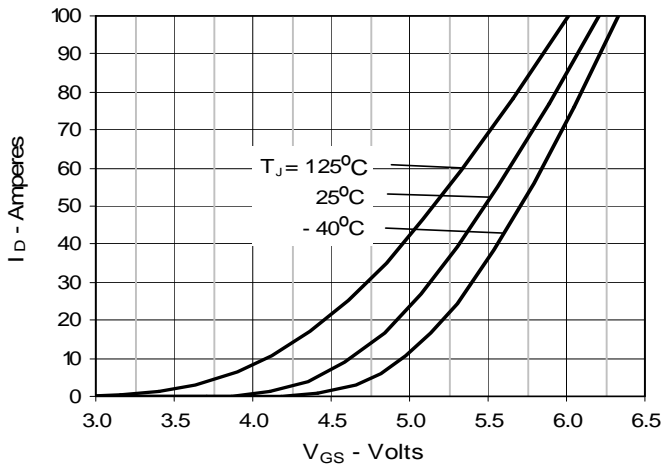


Fig. 8. Transconductance

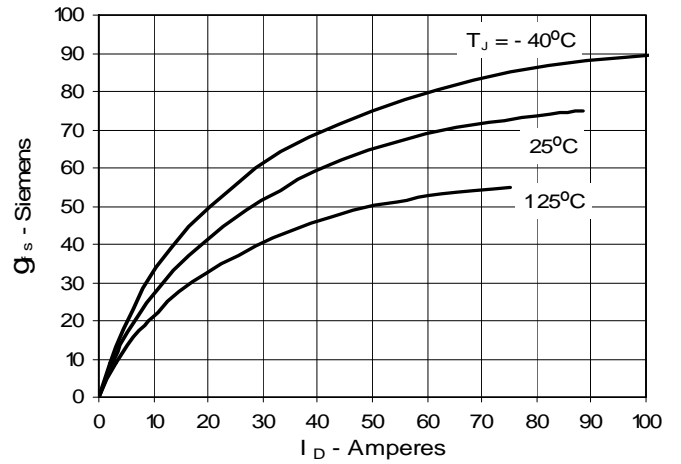


Fig. 9. Source Current vs. Source-To-Drain Voltage

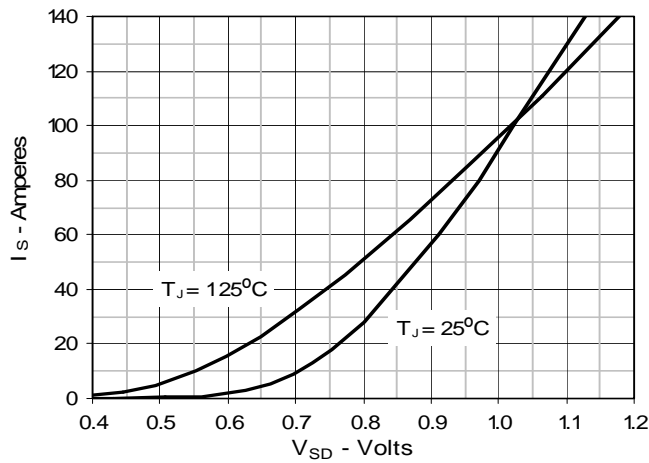


Fig. 10. Gate Charge

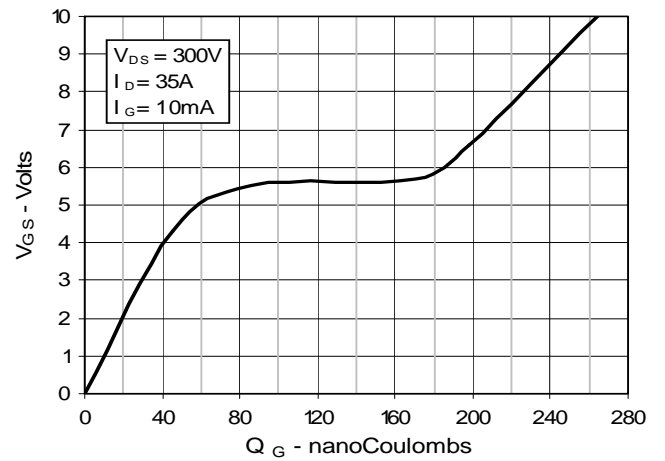


Fig. 11. Capacitance

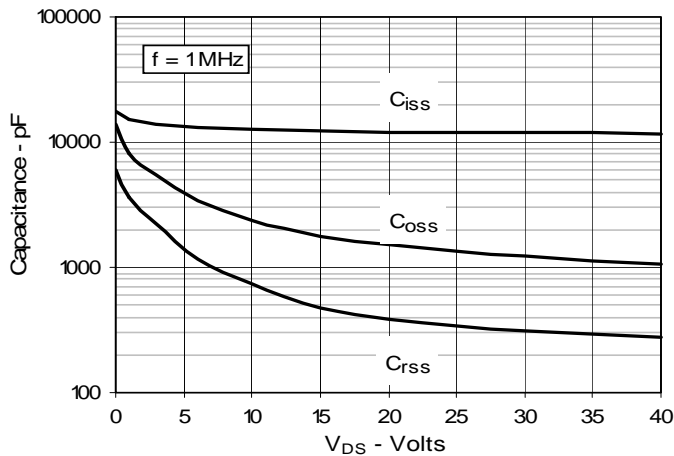


Fig. 12. Maximum Transient Thermal Impedance

